Title (en)

PROCESS AND COMPOSITION FOR TREATING WOOD

Title (de)

VERFAHREN UND ZUSAMMENSETZUNG ZUR BEHANDLUNG VON HOLZ

Title (fr)

PROCEDE ET COMPOSITION DE TRAITEMENT DU BOIS

Publication

EP 1392452 A1 20040303 (EN)

Application

EP 02723715 A 20020329

Priority

- US 0210128 W 20020329
- US 28062001 P 20010330

Abstract (en)

[origin: WO02078865A1] A process for reducing the rate of deterioration of wood that includes contacting the wood with an aqueous alkanline colloidal silicon-containing slat composition that is supersaturated with a boron-containing salt. The contacting may be at ambient or elevated temperature and pressure. The composition is an aqueous colloidal silicon-containing salt that is supersaturated with a boron-containing salt and optionally includes an aluminum salt and a preservative. The composition is made by mixing the boron-containing salt with a colloidal, aqueous mixture of a silicon-containing salt and optionally adding the aluminum salt and the preservative. The process is performed under conditions that result in a supersaturated solution of the boron-containing salt. Wood treated with the composition appears to be resistant to insects, rot, UV deterioration, fire, and other environmental insults. The wood also appears to have increased strength.

IPC 1-7

B05D 1/18; B05D 1/02; B05D 1/28; B05D 3/00; B05D 7/06; B27K 3/16; B27K 3/26; B27K 3/32; C09D 1/02

IPC 8 full level

B27K 3/16 (2006.01); **A01N 25/04** (2006.01); **A01N 37/36** (2006.01); **A01N 59/14** (2006.01); **B05D 1/18** (2006.01); **B05D 7/06** (2006.01); **B27K 3/20** (2006.01); **B27K 3/50** (2006.01); **B27K 3/52** (2006.01); **C09D 1/00** (2006.01)

CPC (source: EP)

A01N 59/00 (2013.01); **A01N 59/14** (2013.01); **B27K 3/163** (2013.01); **B27K 3/32** (2013.01); **B27K 3/52** (2013.01); **C09D 1/00** (2013.01); **C09K 21/02** (2013.01)

C-Set (source: EP)

1. **A01N 59/14** + **A01N 25/04** + **A01N 59/00**
2. **A01N 59/00** + **A01N 25/04**
3. **A01N 59/14** + **A01N 2300/00**

Designated contracting state (EPC)

AT BE CH CY DE DK ES FI FR GB GR IE IT LI LU MC NL PT SE TR

DOCDB simple family (publication)

WO 02078865 A1 20021010; **WO 02078865 A8 20040624**; BR 0208766 A 20040706; CN 1304124 C 20070314; CN 1511068 A 20040707; EP 1392452 A1 20040303; EP 1392452 A4 20041201; JP 2005511262 A 20050428; KR 20040054612 A 20040625; MX PA03008943 A 20120508; PL 368948 A1 20050404; RU 2003131872 A 20050327; RU 2291049 C2 20070110; ZA 200308424 B 20041029

DOCDB simple family (application)

US 0210128 W 20020329; BR 0208766 A 20020329; CN 02809408 A 20020329; EP 02723715 A 20020329; JP 2002577119 A 20020329; KR 20037012870 A 20030930; MX PA03008943 A 20020329; PL 36894802 A 20020329; RU 2003131872 A 20020329; ZA 200308424 A 20020329